

## Ultra-Low Noise Microphone with High Dynamic Range

### GENERAL DESCRIPTION

The ICS-40740 is an ultra-low noise, high dynamic range, differential analog output, bottom-ported MEMS microphone. The ICS-40740 includes a MEMS microphone element, an impedance converter, a differential output amplifier and an enhanced RF package. The ICS-40740's 70 dB SNR and  $\pm 1$  dB sensitivity tolerance make it an excellent choice for microphone arrays and far field voice control applications.

The ICS-40740 has a linear response up to 132.5 dB SPL with a differential output sensitivity specification of  $-37.5$  dBV.

The ICS-40740 is available in a small 4.00 mm  $\times$  3.00 mm  $\times$  1.20 mm surface-mount package.

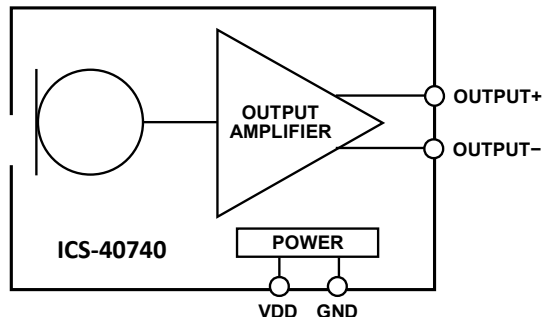
### APPLICATIONS

- Tablet Computers
- Teleconferencing Systems
- Digital Still and Video Cameras
- Communication Headsets
- Security and Surveillance
- Microphone Arrays
- Voice Control and Activation

### FEATURES

- Ultra-High 70 dBA SNR
- $-37.5$  dBV Sensitivity
- $\pm 1$  dB Sensitivity Tolerance
- Small 4  $\times$  3  $\times$  1.2 mm Surface-Mount Package
- Extended Frequency Response from 80 Hz to 20 kHz
- 165  $\mu$ A Current Consumption
- 132.5 dB SPL Acoustic Overload Point
- $-87$  dBV PSR
- Compatible with Sn/Pb and Pb-Free Solder Processes
- RoHS/WEEE Compliant

### FUNCTIONAL BLOCK DIAGRAM



### ORDERING INFORMATION

| PART            | TEMP RANGE                                     | PACKAGING         |
|-----------------|------------------------------------------------|-------------------|
| ICS-40740       | $-40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ | 13" Tape and Reel |
| EV_ICs-40740-FX | —                                              | —                 |

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## SPECIFICATIONS

**TABLE 1. ELECTRICAL CHARACTERISTICS**

$T_A = 25^\circ\text{C}$ ,  $V_{DD} = 1.5$  to  $3.63$  V, unless otherwise noted. Typical specifications are not guaranteed.

| PARAMETER                           | CONDITIONS                                                                 | MIN   | TYP    | MAX   | UNITS         | NOTES |
|-------------------------------------|----------------------------------------------------------------------------|-------|--------|-------|---------------|-------|
| <b>PERFORMANCE</b>                  |                                                                            |       |        |       |               |       |
| Directionality                      |                                                                            |       | Omni   |       |               |       |
| Sensitivity                         | 1 kHz, 94 dB SPL                                                           | -38.5 | -37.5  | -36.5 | dBV           |       |
| Signal-to-Noise Ratio (SNR)         | 20 Hz to 20 kHz, A-weighted                                                |       | 70     |       | dBA           |       |
| Equivalent Input Noise (EIN)        | 20 Hz to 20 kHz, A-weighted                                                |       | 24     |       | dBA SPL       |       |
| Dynamic Range                       | Derived from EIN and maximum acoustic input                                |       | 108.5  |       | dB            |       |
| Frequency Response                  | Low frequency -3 dB point                                                  |       | 77     |       | Hz            | 1     |
|                                     | High frequency -3 dB point                                                 |       | >20    |       | kHz           |       |
| Total Harmonic Distortion (THD)     | 105 dB SPL                                                                 |       |        | 0.3   | %             |       |
| Power-Supply Rejection (PSR)        | 217 Hz, 100 mVp-p square wave superimposed on $V_{DD} = 1.8$ V, A-weighted |       | -87    |       | dBV           |       |
| Power Supply Rejection Ratio (PSRR) | 1 kHz, 100 mV p-p sine wave superimposed on $V_{DD} = 1.8$ V               |       | -85    |       | dB            |       |
| Acoustic Overload Point             | 10% THD                                                                    |       | 132.5  |       | dB SPL        |       |
| <b>POWER SUPPLY</b>                 |                                                                            |       |        |       |               |       |
| Supply Voltage ( $V_{DD}$ )         |                                                                            | 1.5   |        | 3.63  | V             |       |
| Supply Current ( $I_S$ )            |                                                                            |       |        |       |               |       |
|                                     | $V_{DD} = 1.8$ V                                                           |       | 155    |       | $\mu\text{A}$ |       |
|                                     | $V_{DD} = 2.75$ V                                                          |       | 155    |       | $\mu\text{A}$ |       |
| <b>OUTPUT CHARACTERISTICS</b>       |                                                                            |       |        |       |               |       |
| Output Impedance                    |                                                                            |       | 355    |       | $\Omega$      |       |
| Output DC Offset                    | OUTPUT+                                                                    |       | 1.07   |       | V             |       |
|                                     | OUTPUT-                                                                    |       | 1.07   |       | V             |       |
| Maximum Output Voltage              | 132.5 dB SPL input                                                         |       | 1.09   |       | V rms         |       |
| Noise Floor                         | 20 Hz to 20 kHz, A-weighted, rms                                           |       | -107.5 |       | dBV           |       |

**Note 1:** See Figure 3 and Figure 4.

## ABSOLUTE MAXIMUM RATINGS

Stress above those listed as Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to the absolute maximum ratings conditions for extended periods may affect device reliability.

**TABLE 2. ABSOLUTE MAXIMUM RATINGS**

| PARAMETER                   | RATING                                        |
|-----------------------------|-----------------------------------------------|
| Supply Voltage ( $V_{DD}$ ) | -0.3 V to +3.63 V                             |
| Sound Pressure Level        | 160 dB                                        |
| Mechanical Shock            | 10,000 <i>g</i>                               |
| Vibration                   | Per MIL-STD-883 Method 2007, Test Condition B |
| Temperature Range           |                                               |
| Biased                      | -40°C to +85°C                                |
| Storage                     | -55°C to +150°C                               |

## ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

## SOLDERING PROFILE

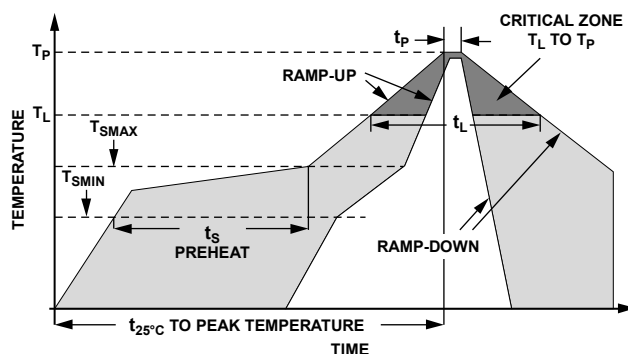


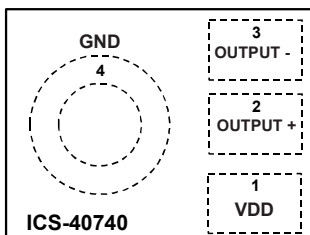
Figure 1. Recommended Soldering Profile Limits

TABLE 3. RECOMMENDED SOLDERING PROFILE\*

| PROFILE FEATURE                                       |                                          | Sn63/Pb37        | Pb-Free          |
|-------------------------------------------------------|------------------------------------------|------------------|------------------|
| Average Ramp Rate ( $T_L$ to $T_P$ )                  |                                          | 1.25°C/sec max   | 1.25°C/sec max   |
| Preheat                                               | Minimum Temperature ( $T_{SMIN}$ )       | 100°C            | 100°C            |
|                                                       | Minimum Temperature ( $T_{SMAX}$ )       | 150°C            | 200°C            |
|                                                       | Time ( $T_{SMIN}$ to $T_{SMAX}$ ), $t_S$ | 60 sec to 75 sec | 60 sec to 75 sec |
| Ramp-Up Rate ( $T_{SMAX}$ to $T_L$ )                  |                                          | 1.25°C/sec       | 1.25°C/sec       |
| Time Maintained Above Liquidous ( $t_L$ )             |                                          | 45 sec to 75 sec | ~50 sec          |
| Liquidous Temperature ( $T_L$ )                       |                                          | 183°C            | 217°C            |
| Peak Temperature ( $T_P$ )                            |                                          | 215°C +3°C/-3°C  | 260°C +0°C/-5°C  |
| Time Within +5°C of Actual Peak Temperature ( $t_P$ ) |                                          | 20 sec to 30 sec | 20 sec to 30 sec |
| Ramp-Down Rate                                        |                                          | 3°C/sec max      | 3°C/sec max      |
| Time +25°C ( $t_{25°C}$ ) to Peak Temperature         |                                          | 5 min max        | 5 min max        |

**\*Note:** The reflow profile in Table 3 is recommended for board manufacturing with InvenSense MEMS microphones. All microphones are also compatible with the J-STD-020 profile

## PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS



TOP VIEW  
(TERMINAL SIDE DOWN)  
Not to Scale

Figure 2. Pin Configuration

TABLE 4. PIN FUNCTION DESCRIPTIONS

| PIN | NAME     | FUNCTION               |
|-----|----------|------------------------|
| 1   | VDD      | Power Supply           |
| 2   | OUTPUT + | Analog Output Signal + |
| 3   | OUTPUT - | Analog Output Signal - |
| 4   | GND      | Ground                 |

## TYPICAL PERFORMANCE CHARACTERISTICS

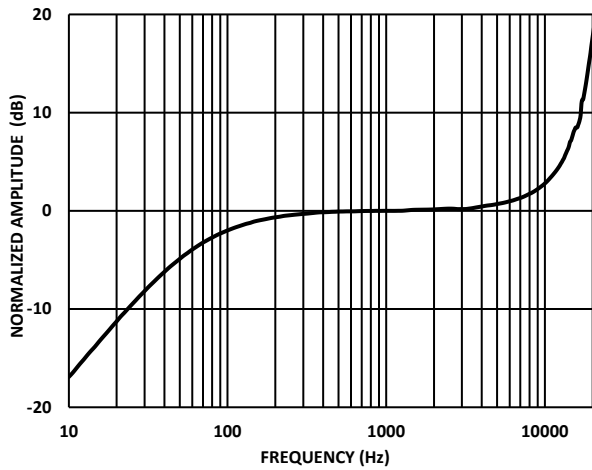


Figure 3. Typical Frequency Response (Measured)

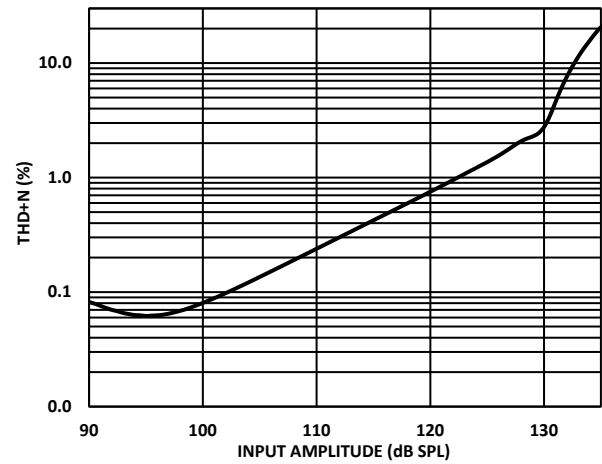


Figure 4. THD + N vs. Input Level

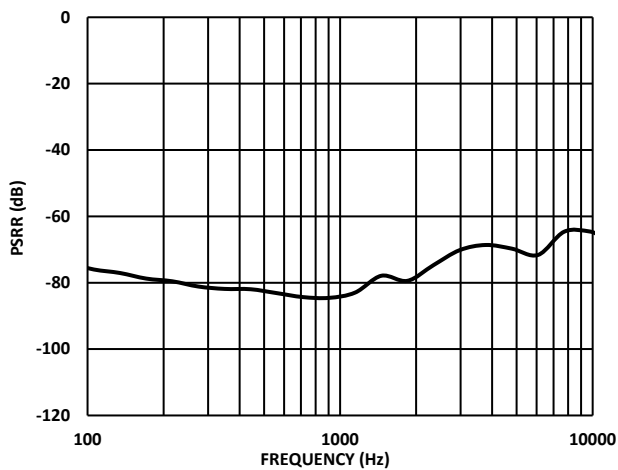


Figure 5. Power-Supply Rejection Ratio (PSRR) vs. Frequency

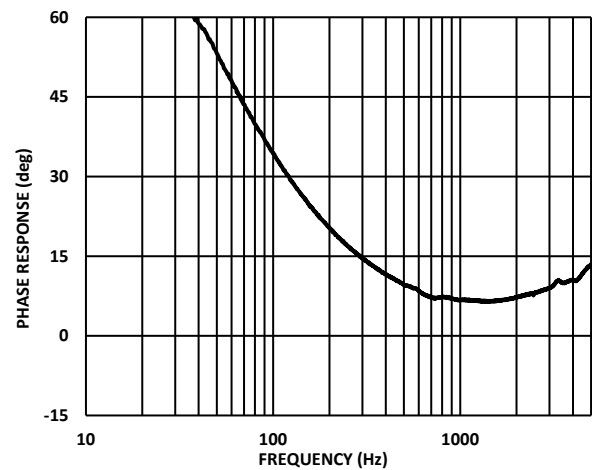


Figure 6. Phase vs. Frequency

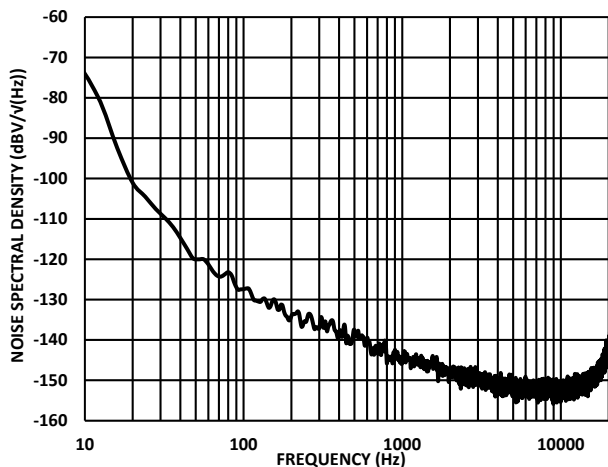


Figure 7. Noise Floor

## THEORY OF OPERATION

### BALANCED OUTPUT

The ICS-40740 has a balanced differential output with 355  $\Omega$  output impedance. This configuration is compatible with a fully-differential codec input and provides the benefits of a balanced signal between the microphone and codec. A balanced analog audio signal provides rejection of common-mode noise that is present on both the positive and negative signals.

## APPLICATIONS INFORMATION

### CODEC CONNECTION

The ICS-40740 output can be connected to a dedicated codec microphone input (see Figure 9) or to a high input impedance gain stage. A 0.1  $\mu\text{F}$  ceramic capacitor placed close to the ICS-40740 supply pin is used for testing and is recommended to adequately decouple the microphone from noise on the power supply. DC blocking capacitors are required at the outputs of the microphone. These capacitors create a high-pass filter with a corner frequency at

$$f_c = 1/(2\pi \times C \times R)$$

where  $R$  is the input impedance of the codec.

A minimum value of 2.2  $\mu\text{F}$  is recommended in Figure 9 because the input impedance of some codecs can be as low as 2 k $\Omega$  at their highest PGA gain setting, which results in a high-pass filter corner frequency at 37 Hz.

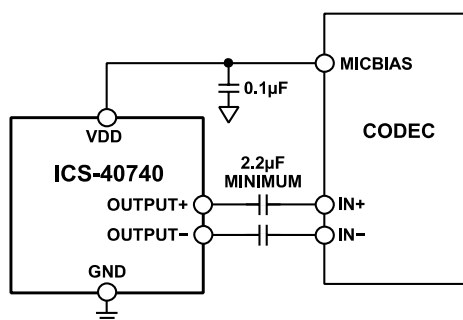


Figure 8. ICS-40740 Connected to a Codec



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## **SUPPORTING DOCUMENTS**

For additional information, see the following documents.

### **EVALUATION BOARD USER GUIDE**

AN-#####

### **APPLICATION NOTES**

AN-100, *MEMS Microphone Handling and Assembly Guide*

AN-1003, *Recommendations for Mounting and Connecting the InvenSense Bottom-Ported MEMS Microphones*

AN-1112, *Microphone Specifications Explained*

AN-1124, *Recommendations for Sealing InvenSense Bottom-Port MEMS Microphones from Dust and Liquid Ingress*

AN-1140, *Microphone Array Beamforming*

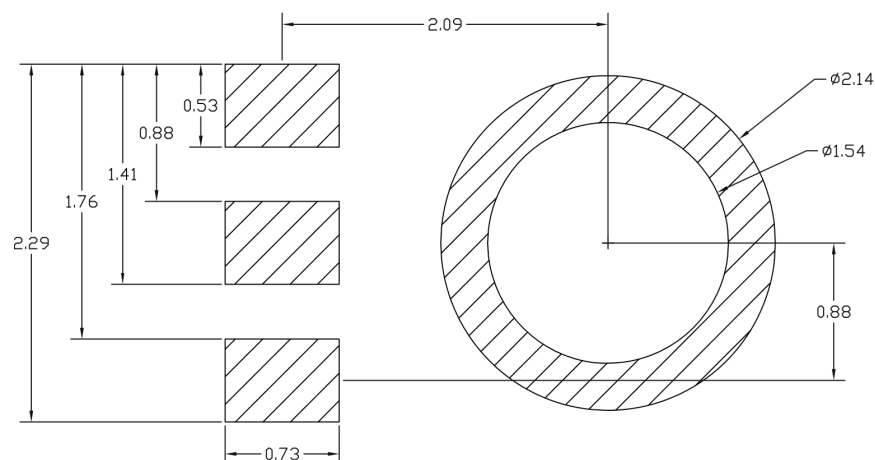
AN-1165, *Op Amps for Microphone Preamp Circuits*

AN-1181, *Using a MEMS Microphone in a 2-Wire Microphone Circuit*

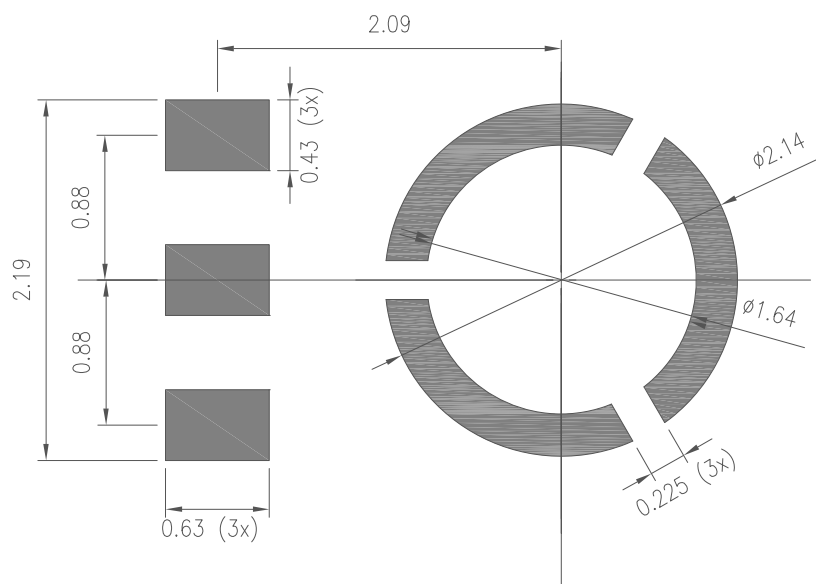
## PCB DESIGN AND LAND PATTERN LAYOUT

Lay out the PCB land pattern for the ICS-40740 at a 1:1 ratio to the solder pads on the microphone package (see Figure 10.) Take care to avoid applying solder paste to the sound hole in the PCB. Figure 11 shows a suggested solder paste stencil pattern layout. The response of the ICS-40740 is not affected by the PCB hole size, as long as the hole is not smaller than the sound port of the microphone (0.75 mm, or 0.0295 inch, in diameter). A 1 mm (0.040 inch) diameter for the hole is recommended.

Align the hole in the microphone package with the hole in the PCB. The exact degree of the alignment does not affect the performance of the microphone as long as the holes are not partially or completely blocked.



**Figure 9. Suggested PCB Land Pattern Layout**



Note : All units in mm

**Figure 10. Suggested Solder Paste Stencil Pattern Layout**

## PCB MATERIAL AND THICKNESS

The performance of the ICS-40740 is not affected by PCB thickness. The ICS-40740 can be mounted on either a rigid or flexible PCB. A flexible PCB with the microphone can be attached directly to the device housing with an adhesive layer. This mounting method offers a reliable seal around the sound port while providing the shortest acoustic path for good sound quality.

## **HANDLING INSTRUCTIONS**

### **PICK AND PLACE EQUIPMENT**

The MEMS microphone can be handled using standard pick-and-place and chip shooting equipment. Take care to avoid damage to the MEMS microphone structure as follows:

- Use a standard pickup tool to handle the microphone. Because the microphone hole is on the bottom of the package, the pickup tool can make contact with any part of the lid surface.
- Do not pick up the microphone with a vacuum tool that makes contact with the bottom side of the microphone.
- Do not pull air out of or blow air into the microphone port.
- Do not use excessive force to place the microphone on the PCB.

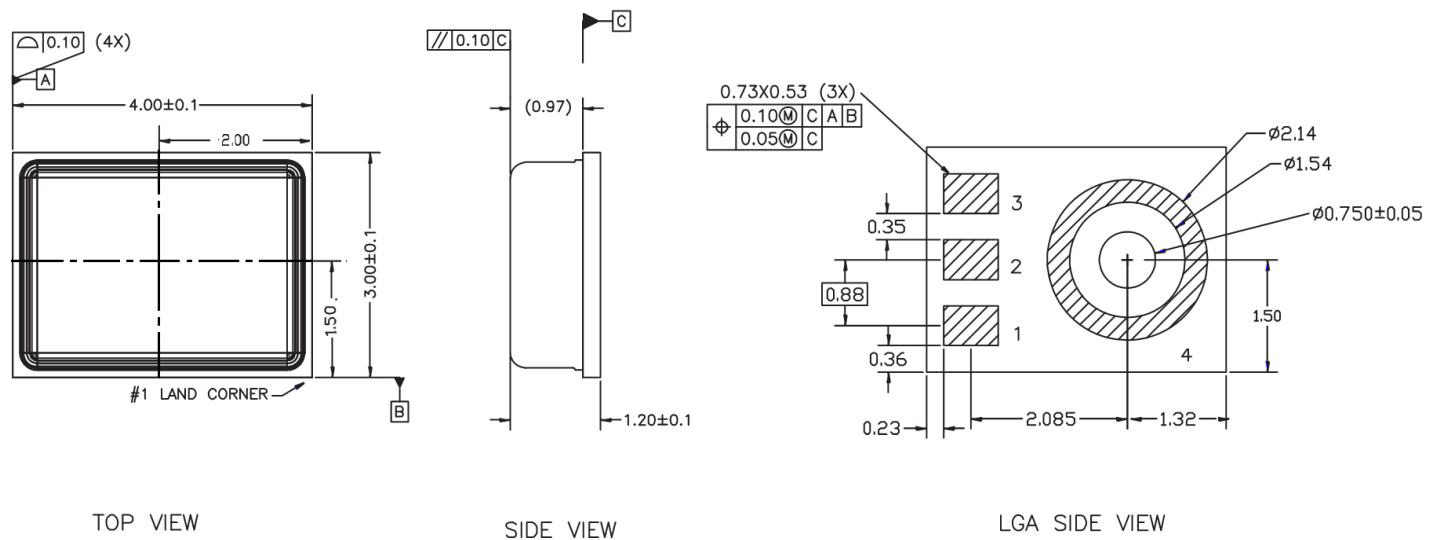
### **REFLOW SOLDER**

For best results, the soldering profile must be in accordance with the recommendations of the manufacturer of the solder paste used to attach the MEMS microphone to the PCB. It is recommended that the solder reflow profile not exceed the limit conditions specified in Figure 1 and Table 3.

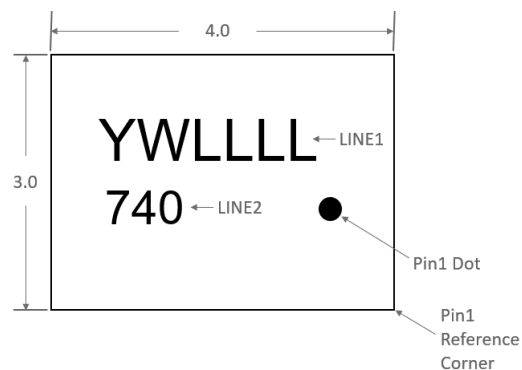
### **BOARD WASH**

When washing the PCB, ensure that water does not make contact with the microphone port. Do not use blow-off procedures or ultrasonic cleaning.

## OUTLINE DIMENSIONS



**Figure 11. 4-Terminal Chip Array Small Outline No Lead Cavity**  
**4 mm × 3 mm × 1.2 mm**  
**Dimensions shown in millimeters**



**Figure 12. Package Marking Specification (Top View)**

## ORDERING GUIDE

| PART            | TEMP RANGE     | PACKAGE               | QUANTITY | PACKAGING         |
|-----------------|----------------|-----------------------|----------|-------------------|
| ICS-40740       | -40°C to +85°C | 4-Terminal LGA_CAV    | 5000     | 13" Tape and Reel |
| EV_ICs-40740-FX |                | Flex Evaluation Board |          |                   |

**REVISION HISTORY**

| REVISION DATE | REVISION | DESCRIPTION     |
|---------------|----------|-----------------|
| 09/07/2018    | 1.0      | Initial Release |
| 4/20/2020     | 1.1      | Corrected typos |

## **COMPLIANCE DECLARATION DISCLAIMER**

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